

ABSTRACT

To provide a sputtering target for magnetic materials, a sputtering target assembly for magnetic materials, and a method for producing a sputtering target for magnetic materials that can effectively suppress peeling of a redeposited film.

The sputtering target for magnetic materials has a sputtering region and a non-sputtering region, wherein an arithmetic mean curvature Spc of peaks on a surface of the non-sputtering region is 3200 mm^{-1} or more.